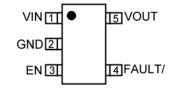
Ordering Information

Part Number	Marking	Current Limit	Current-Limit Recovery	Junction Temperature Range	Package
MIC2090-1YM5	<u>L1</u> K	50mA	Auto-Retry	–40°C to +125°C	SOT-23-5
MIC2091-1YM5	<u>M1</u> K	100mA	Auto-Retry	–40°C to +125°C	SOT-23-5
MIC2090-2YM5	<u>L2</u> K	50mA	Latch-Off	–40°C to +125°C	SOT-23-5
MIC2091-2YM5	<u>M2</u> K	100mA	Latch-Off	–40°C to +125°C	SOT-23-5

Pin Configuration



5-Pin SOT-23 (M5)

Pin Description

Pin Number	Pin Name	Pin Function		
1	VIN	Supply (Input): +1.8V to +5.5V. Provides power to the output switch and the MIC2090/MIC209 internal control circuitry.		
2	GND	Ground.		
3	EN	Enable (Input): Active-high TTL compatible control input. A high signal turns on the internal switch and supplies power to the load. This pin cannot be left floating.		
4 FAULT/		 Fault Status (Output): Open drain output. Can be connected to other open drain outputs. Must be pulled high with an external resistor. When EN=0, FAULT/ pin is high When EN=1, a low on the FAULT/ pin indicates one or more of the following conditions: 		
		 The part is in current limit and is turned off. The part is in thermal limit and is turned off. The part is in UVLO 		
5	VOUT	Switched Output (Output): The voltage on this pin is controlled by the internal switch. Connect the load driven by the MIC2090/MIC2091 to this pin.		

Absolute Maximum Ratings⁽¹⁾

Supply Voltage (V _{IN})	0.3V to +6.0V
Output Voltage (V _{OUT}).	
FAULT/ Pin Voltage (V _{FAULT/})	0.3V to +6.0V
FAULT/ Pin Current (I FAULT/)	25mA
EN Pin Voltage (V _{EN})	-0.3V to (V _{IN} + 0.3V)
Power Dissipation (P _D)	Internally Limited
Maximum Junction Temperature (T _J)	150°C
Storage Temperature (T _S)	
Lead Temperature (soldering, 10s)	
ESD HBM Rating ⁽³⁾	3kV
Lead Temperature (soldering, 10s) ESD HBM Rating ⁽³⁾ ESD MM Rating ⁽³⁾	200V

Operating Ratings⁽²⁾

Supply Voltage (V _{IN})	+1.8V to +5.5V
Output Voltage (V _{OUT})	+1.8V to +5.5V
EN Pin Voltage (V _{EN})	0V to V _{IN}
FAULT/ Pin Voltage (V _{FAULT/})	0V to 5.5V
FAULT/ Pin Current (I FAULT/)	1mA
Ambient Temperature (T _A)	–40°C to +85°C
Junction Temperature (T _J)	–40°C to +125°C
Package Thermal Resistance	
SOT23-5 (θ _{JA})	252.7°C/W

Electrical Characteristics⁽⁴⁾

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units	
Power Input	t Supply			1			
V _{IN}	Input Voltage Range		1.8		5.5	V	
I _{VIN}	Shutdown Current	$V_{EN} \leq 0.5 V$ (switch off), V_{OUT} = open		5	10	μA	
	Supply Current	$V_{EN} \ge 1.5V$ (switch on), V_{OUT} = open		70	110		
V _{UVLO}	Under-Voltage Lockout Threshold	V _{IN} rising			1.75	V	
V _{UVLO_HYS}	Under-Voltage Lockout Threshold Hysteresis			100		mV	
Enable Inpu	it						
M	Enable Logic Level High ⁽⁵⁾	V _{IH (MIN)}	1.5			V	
V _{EN}	Enable Logic Level Low ⁽⁵⁾	V _{IL (MAX)}			0.5		
I _{EN}	Enable Bias Current	V _{EN} = 5V		0.1		μA	
t _{ON}	Output Turn-On Delay	R_L = 500 Ω , C_L = 0.1 μ F See "Timing Diagrams"		215		μs	
t _R	Output Turn-On Rise Time	R_L = 500 Ω , C_L = 0.1 μ F See "Timing Diagrams"		5		μs	
t _{OFF}	Output Turn-Off Delay	R_L = 500 Ω , C_L = 0.1 μ F See "Timing Diagrams"		125		μs	
t _F	Output Turn-Off Fall Time	R_L = 500 Ω , C_L = 0.1 μ F See "Timing Diagrams"		115		μs	
Internal Swi	itch						
	On Resistance R _{DS(ON)}	MIC2090 V _{IN} = 5.0V, I _{OUT} = 50mA		700	1200	mΩ	
		MIC2090 V _{IN} = 3.3V, I _{OUT} = 50mA		790	1200		
P		MIC2090 V _{IN} = 1.8V, I _{OUT} = 50mA		1300			
R _{DSON}		MIC2091 V _{IN} = 5.0V, I _{OUT} = 100mA		700	1200		
		MIC2091 V _{IN} = 3.3V, I _{OUT} = 100mA		790	1200		
		MIC2091 V _{IN} = 1.8V, I _{OUT} = 100mA		1300			
	Input-to-Output Leakage Current (Forward leakage Current)	MIC2090 and MIC2091, $V_{\text{EN}} \leq 0.5 V,$ (output off), V_{IN} = 5.5V, V_{OUT} = 0V			10	μΑ	

Electrical Characteristics⁽⁴⁾ (Continued)

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units	
	Output to Input Leakage Current (Reverse Leakage Current)	MIC2090 and MIC2091, $V_{EN} \leq$ 0.5V, (output off), V_{OUT} = 5.5V, V_{IN} = 0V			10	μA	
Current Limit	t						
		MIC2090 @ V _{OUT} = 4.5V	50	75	100		
1		MIC2090 @ V _{OUT} = 0V	50	100	150	m 4	
LIMIT	Current-Limit Threshold	MIC2091 @ V _{OUT} = 4.5V	100	150	200	- mA	
		MIC2091 @ V _{OUT} = 0V	100	175	250		
t _{SC_RESP}	Short-Circuit Response Time	Short circuit applied to output after switch is turned on, see "Timing Diagrams". $V_{IN} = 3.3V$.		20		ns	
Tautorestart	Time After Switch Shuts Down From An Over- Current Condition Before It Tries To Turn On Again.		30	60	90	ms	
FAULT/ Flag		· · · · · · · · · · · · · · · · · · ·			1		
	Error Flag Output Voltage	Output voltage high (1mA Sinking)			0.4	V	
t _{D_FAULT/}	Time After Switch Comes Into Current Limit Before The PIN FAULT/ Is Pulled Low.	When an over-current condition happens, the part will go into constant output current for this time. After this time it will turn off the output and pull low the PIN FAULT/. The MIC2090-1 and MIC2091-1 will automatically restart themselves after the auto restart time T _{AUTORESTART} .	5	10	20	ms	
t _{R_FAULT/}	FAULT/ Rising Time	FAULT/ is connected to V_{IN} = 5V through 10k Ω and 100pF in parallel. See "Timing Diagrams"		5		μs	
t _{F_FAULT}	FAULT/ Falling Time			1		μs	
Reverse Volt	age Protection (OGI)						
OGI	Output Voltage Greater Than Input Voltage (OGI)	If the output voltage is greater than the input voltage by this amount, the part will shut down. The enable pin must be recycled to reset.		85		mV	
OGI _{TIME}		Time that the output voltage can be greater than the input voltage before the chip is shut down.		10		ms	
Thermal Prot	ection						
T	Over-Temperature	T _J Rising		150		°C	
TOVERTEMP	Shutdown	T _J Falling		140		°C	

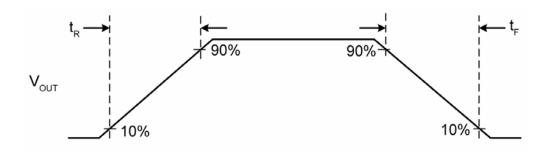
 V_{IN} = 5V; T_{A} = 25°C, **bold** values indicate –40°C $\leq T_{\text{A}} \leq +85^{\circ}C$, unless noted.

Notes:

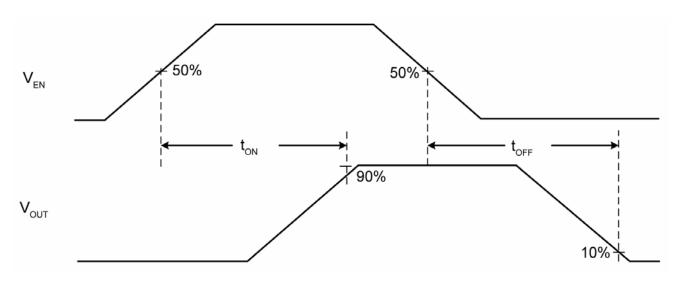
- 2. The device is not guaranteed to function outside its operating rating.
- 3. Devices are ESD sensitive. Handling precautions recommended. Human body model, 1.5k in series with 100pF.
- 4. Specification for packaged product only.
- V_{IL(MAX)} = Maximum positive voltage applied to the input which will be accepted by the device as a logic low. V_{IH(MIN)} = Minimum positive voltage applied to the input which will be accepted by the device as a logic high.

^{1.} Exceeding the absolute maximum rating may damage the device.

Timing Diagrams

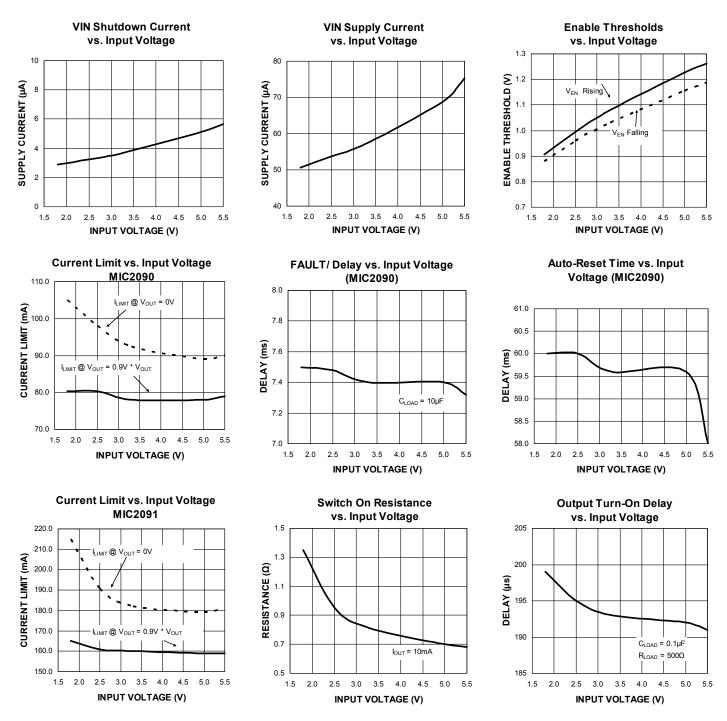




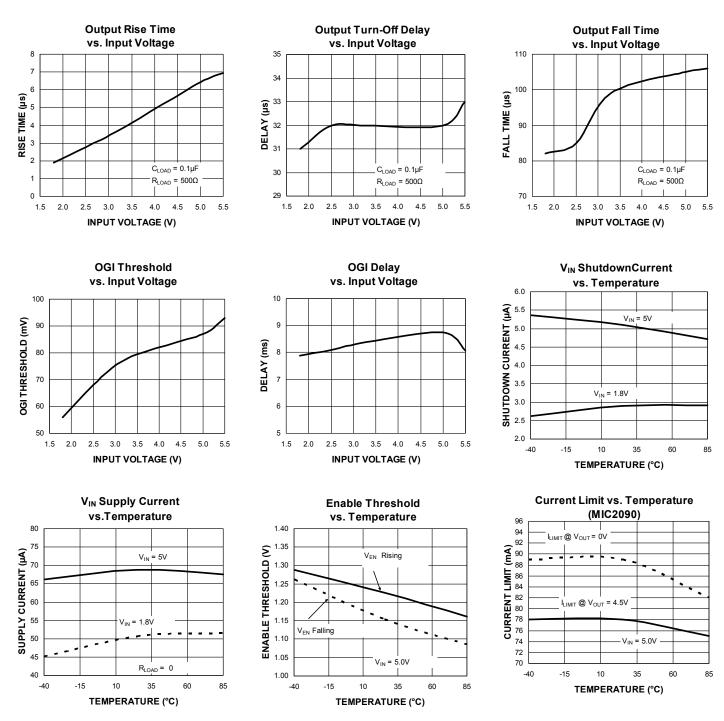


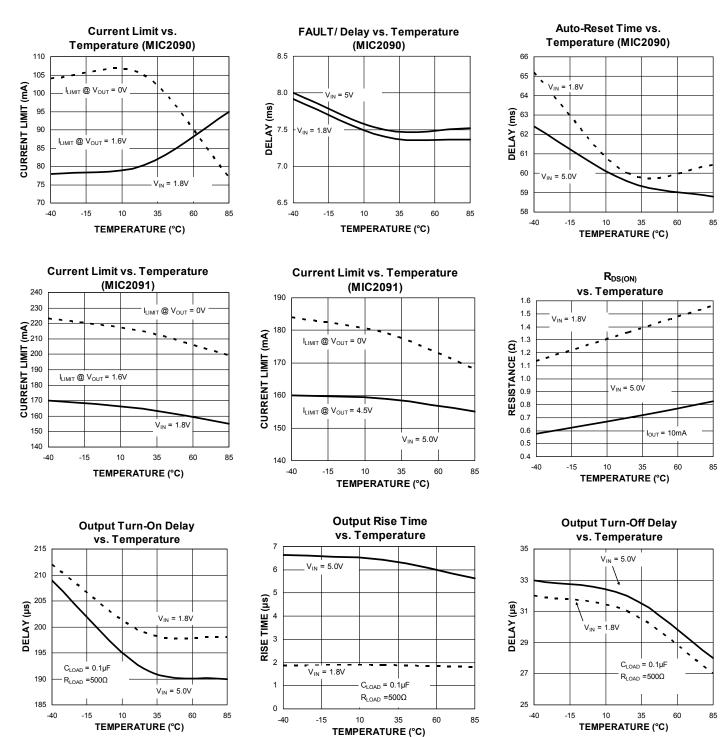
Switch Delay Time (ton, toff)

Typical Characteristics



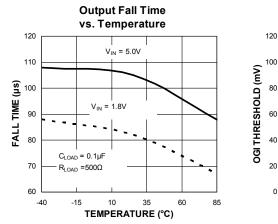
Typical Characteristics (Continued)

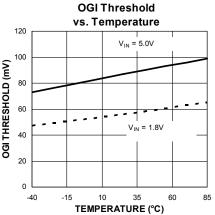


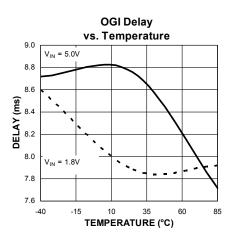


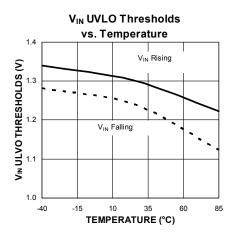
Typical Characteristics (Continued)

Typical Characteristics (Continued)

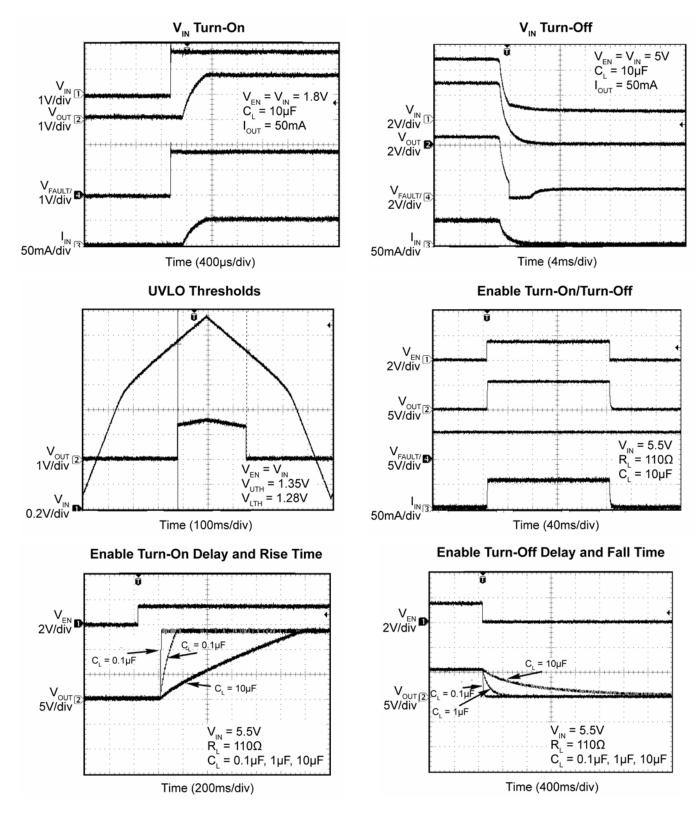


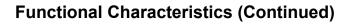


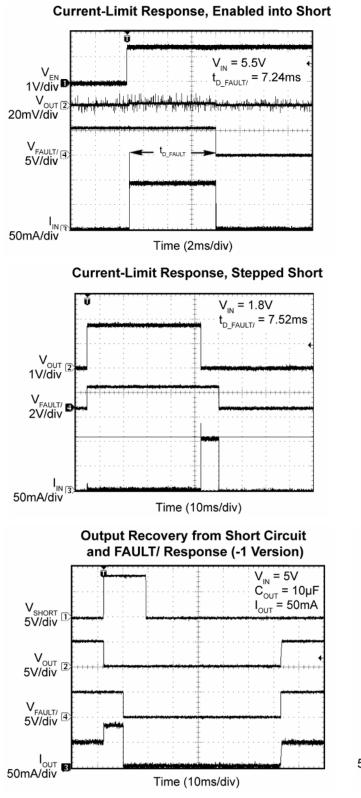




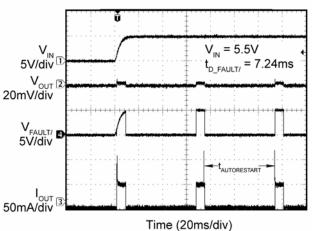
Functional Characteristics



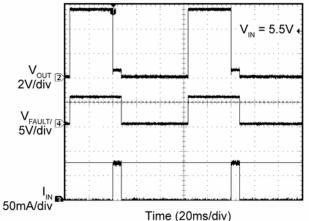




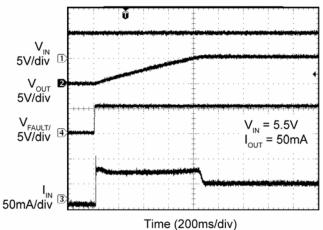
Power-Up into Short Circuit (-1 Version)



Current-Limit Response, Stepped Overcurrent

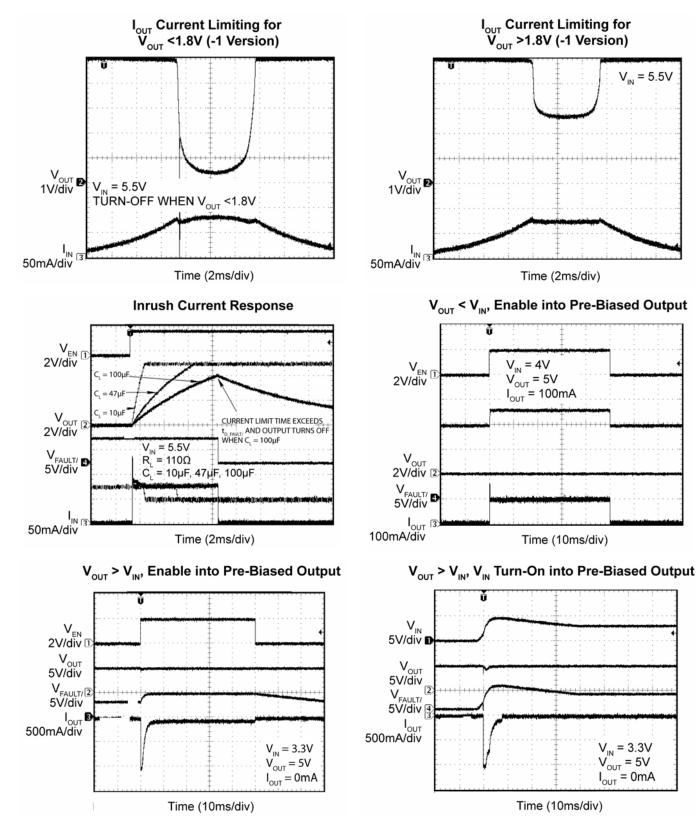


Output Recovery from Thermal Shutdown and FAULT/ Response



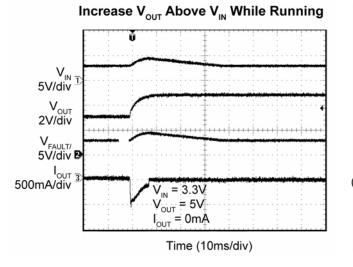
V_{IN} = 5.5V



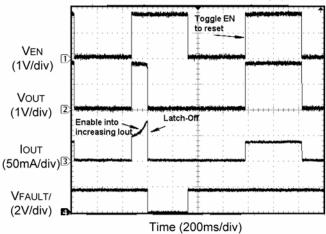


 $V_{IN} = 3.3V$ $V_{OUT} = 5V$ $I_{OUT} = 0mA$

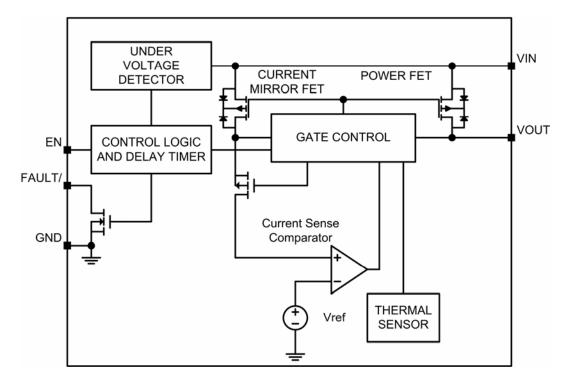
Functional Characteristics (Continued)



Overcurrent Lathch-Off and Recovery (-2 Version)



Functional Diagram



MIC2090/MIC2091 Functional Diagram

Functional Description

V_{IN} and V_{OUT}

 V_{IN} is both the power supply connection for the internal circuitry driving the switch and the input (source connection) of the power MOSFET switch. V_{OUT} is the drain connection of the power MOSFET and supplies power to the load. In a typical circuit, current flows from V_{IN} to V_{OUT} toward the load.

When the switch is disabled, current will not flow to the load, except for a small unavoidable leakage current of a few microamps (forward leakage current).

CIN

A minimum 1µF bypass capacitor positioned close to the V_{IN} and GND pins of the switch is both good design practice and required for proper operation of the switch. This will control supply transients and ringing. Without a sufficient bypass capacitor, large current surges or a short may cause sufficient ringing on V_{IN} (from supply lead inductance) to cause erratic operation of the switch's control circuitry. For best performance, place a ceramic capacitor next to the IC.

An additional 10μ F (or greater) capacitor, positioned close to the VIN and GND pins of the switch is necessary if the distance between a larger bulk capacitor and the switch is greater than three inches. This additional capacitor limits input voltage transients at the switch caused by fast changing input currents that occur during a fault condition, such as current limit and thermal shutdown.

When bypassing with capacitors of 10μ F or more, it is good practice to place a smaller value capacitor in parallel with the larger to handle the high-frequency components of any line transients. Values in the range of 0.1μ F to 1μ F are recommended. Again, good quality, low-ESR capacitors, preferably ceramic, should be chosen.

$\mathbf{C}_{\mathsf{OUT}}$

An output capacitor is required to reduce ringing and voltage sag on the output during a transient condition. A value between 1μ F and 10μ F is recommended.

A 10μ F or larger capacitor should be used if the distance between the MIC2090/MIC2091 and the load is greater than three inches. The internal switch in the MIC2090/MIC2091 turns off in (typically) 20ns. This extremely fast turn-off can cause an inductive spike in the output voltage when the internal switch turns off during an overcurrent condition. The larger value capacitor prevents the output from glitching too low.

Limitations on COUT

The part may enter current limit when turning on with a large output capacitance, which is an acceptable condition. However, if the part remains in current limit for a time greater than t_{D_FAULT} , the FAULT/ pin will assert low. The maximum value of C_{OUT} may be approximated by Equation 1:

$$C_{OUT_MAX} = \frac{I_{LIMIT_MIN} \times T_{D_FAULT_MIN}}{V_{IN_MAX}} \qquad \text{Eq. 1}$$

Where: $I_{\text{LIMIT_MIN}}$ and $T_{\text{D}_FAULT_MIN}$ are the minimum specified values listed in the Electrical Characteristic table and V_{IN_MAX} is the maximum input voltage to the switch.

Current Sensing and Limiting

The MIC2090/MIC2091 protects the system power supply and load from damage by continuously monitoring current through the on-chip power MOSFET. Load current is monitored by means of a current mirror in parallel with the power MOSFET switch. Current limiting is invoked when the load exceeds the overcurrent threshold. When current limiting is activated in the -1 version, the output current is constrained to the limit value, and remains at this level until either the load/fault is removed, the load's current requirement drops below the limiting value, or the switch goes into thermal shutdown. If the overcurrent fault is large enough to drop V_{OUT} below (typically) 1.8V, the internal MOSFET turns off very quickly (typically 20ns). This prevents excessive current from flowing through the device and damaging the internal MOSFET.

The latch-off feature of the -2 version latches the output off when the output current exceeds the overcurrent threshold. V_{IN} or the enable pin must be toggled to reset the latch.

Enable Input

The EN pin is a TTL logic level compatible input which turns the internal MOSFET switch on and off. The FAULT/ pin remains high when the EN pin is pulled low and the output is turned off. Toggling the enable pin resets the output after an OGI (output greater than input) condition occurs. In the -2 version, toggling the enable pin resets the output after an overcurrent event.

Fault Output

The FAULT/ is an N-channel open-drain output, which is asserted LOW when the MIC2090/MIC2091 switch either begins current limiting or enters thermal shutdown.

During an overcurrent or short circuit, The FAULT/ signal asserts after a brief delay period, $t_{D_FAULT/}$, in order to filter out false or transient over-current conditions.

The FAULT/ output is open-drain and must be pulled HIGH with an external resistor. The FAULT/ signal may be wire-OR'd with other similar outputs, sharing a single pull-up resistor.

Power Dissipation and Thermal Shutdown

Thermal shutdown is used to protect the MIC2090/MIC2091 switch from damage should the die temperature exceed a safe operating temperature. Thermal shutdown shuts off the output MOSFET and asserts the FAULT/ output if the die temperature reaches the over-temperature threshold, T_{OVERTEMP}.

The switch will automatically resume operation when the die temperature cools down to 140°C. If resumed operation results in reheating of the die, another shutdown cycle will occur and the switch will continue cycling between ON and OFF states until the reason for the overcurrent condition has been resolved.

Depending upon the PCB layout, package type, ambient temperature, etc., hundreds of milliseconds may elapse from the time a fault occurs to the time the output MOSFET will be shut off. This delay is caused because of the time it takes for the die to heat after the fault condition occurs.

Power dissipation depends on several factors such as the load, PCB layout, ambient temperature, and supply voltage. Calculation of power dissipation can be accomplished by Equation 2:

$$P_{D} = R_{DS(ON)} \times (I_{OUT})^{2}$$
 Eq.2

To relate this to junction temperature, Equation 3 can be used:

$$T_{J} = P_{D} \times R_{\theta(J-A)} + T_{A}$$
 Eq. 3

Where:

 T_J = Junction Temperature T_A = Ambient Temperature

 $R_{\theta(J-A)}$ is the thermal resistance of the package.

In normal operation, excessive switch heating is most often caused by an output short circuit. If the output is shorted, when the switch is enabled, the MIC2090/MIC2091 switch limits the output current to the maximum value. The heat generated by the power dissipation of the switch continuously limiting the current

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may exceed the package and PCB's ability to cool the device and the MIC2090/MIC2091 will shut down and signal a fault condition. Please see the "Fault Output" description for more details on the FAULT/ output.

After the MIC2090/MIC2091 shuts down, and cools, it will re-start itself if the enable signal remains true.

n Figure 2, die temperature is plotted against I_{OUT} assuming a constant ambient temperature of 85°C and a worst case internal switch on-resistance (R_{ON}). This plot is valid for both the MIC2090 and MIC2091.

Die Temperature vs. Output Current (Ambient Temperature = 85°C)

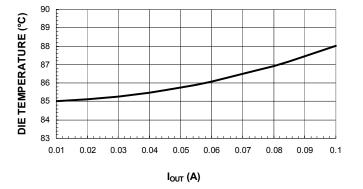


Figure 2. Die Temperature vs. IOUT

I_{LIMIT} vs. I_{OUT} Measured (-1 version only)

When the MIC2090/MIC2091 is current limiting, it is designed to act as a constant current source to the load. As the load tries to pull more than the maximum current, V_{OUT} drops and the input to output voltage differential increases. When V_{OUT} drops below 1.8V, then the output switch momentarily turns off to insure the internal MOSFET switch is not damaged by a very fast short circuit event.

When measuring I_{OUT} in an overcurrent condition, it is important to remember voltage dependence, otherwise the measurement data may appear to indicate a problem when none really exists. This voltage dependence is illustrated in Figures 3 and 4.

In Figure 3, output current is measured as V_{OUT} is pulled below V_{IN}, with the test terminating when V_{OUT} is 2.5V below V_{IN}. Observe that once I_{LIMIT} is reached I_{OUT} remains constant throughout the remainder of the test.

Figure 4 repeats this test but simulates operation deeper into an overcurrent condition. When V_{OUT} drops below 1.8V, the switch turns off for a few microseconds before turning back on.

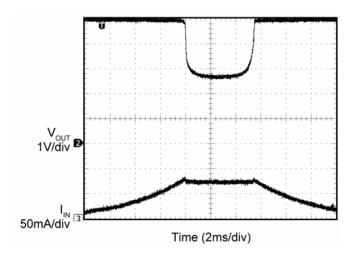


Figure 3. I_{OUT} in Current Limiting for $V_{OUT} > 1.8V$

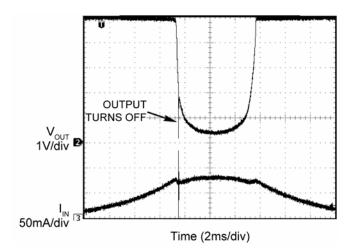


Figure 4. I_{OUT} in Current Limiting for $V_{OUT} < 1.8V$

Under-Voltage Lock Out (UVLO)

The MIC2090/MIC2091 switches have an Under-Voltage Lock Out (UVLO) feature that will shut down the switch in a reproducible way when the input power supply voltage goes too low. The UVLO circuit disables the output until the supply voltage exceeds the UVLO threshold. Hysteresis in the UVLO circuit prevents noise and finite circuit impedance from causing chatter during turn-on and turn-off. While disable by the UVLO circuit, the output switch (power MOSFET) is OFF and no circuit functions, such as FAULT/ or EN, are considered to be valid or operative.

OGI (Output Greater than Input)

The internal MOSFET switch turns off when it senses an output voltage that is greater than the input voltage. This feature prevents continuous current from flowing from the output to the input.

If the output voltage rises above V_{IN} by the OGI threshold voltage (typically 85mV), the internal MOSFET switch turns off after a period of time, specified in the electrical characteristics table as OGI_{TIME}. The FAULT/ pin remains high during and after an OGI event.

Figure 5 shows the output voltage, input current and FAULT/ pin voltage when the output voltage is raised above the input. Reverse current flows through the internal MOSFET switch for the OGI_{TIME} period, until the internal MOSFET switch is turned off and the input current goes to 0A.

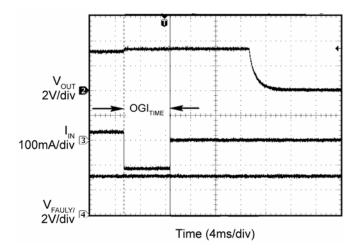
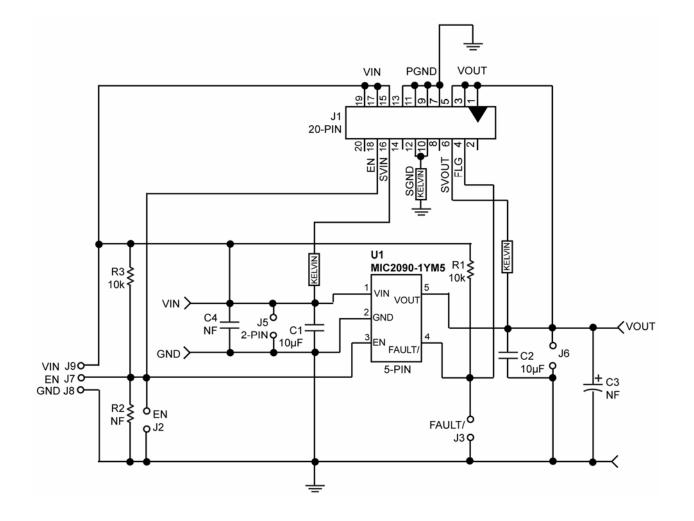


Figure 5. OGI Event

MIC2090/MIC2091 Evaluation Board Schematic



Bill of Materials

ltem	Part Number	Manufacturer	Description	Qty.
C1, C2	08056D106MAT2A	AVX ⁽¹⁾	10µF, 6.3V Ceramic Capacitor, X5R	2
C3, C4			NF (No Fill)	2
R1, R3	CRCW06031002FRT1	Vishay Dale ⁽²⁾	10k, 1%, 0603 Resistor	2
R2			NF (No Fill)	1
U1	MIC2090-1YM5	Micrel, Inc. ⁽³⁾	Current Limiting Power Distribution Switch	1
U1	MIC2091-1YM5	Micrel, Inc. ⁽³⁾	Current Limiting Power Distribution Switch	0
U1	MIC2090-2YM5	Micrel, Inc. ⁽³⁾	Current Limiting Power Distribution Switch	0
U1	MIC2091-2YM5	Micrel, Inc. ⁽³⁾	Current Limiting Power Distribution Switch	0

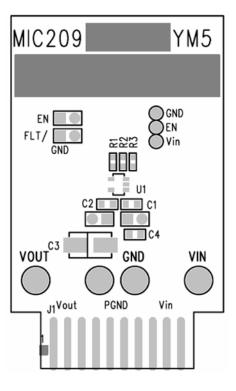
Notes:

1. AVX: <u>www.avx.com</u>.

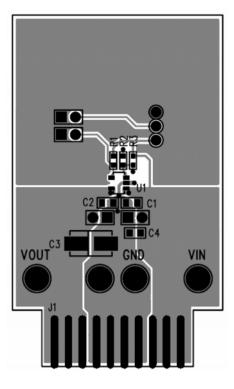
2. Vishay Tel: <u>www.vishay.com</u>.

3. Micrel, Inc.: <u>www.micrel.com</u>.

PCB Layout Recommendations

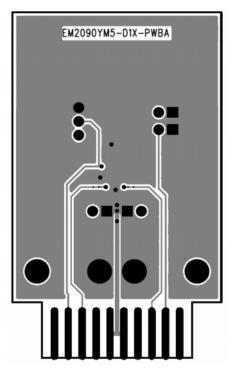


Top Silk Screen

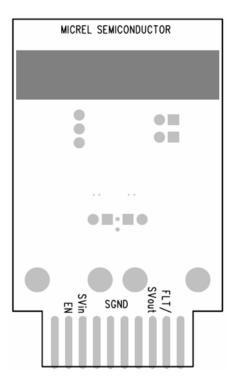


Top Copper

PCB Layout Recommendations (Continued)

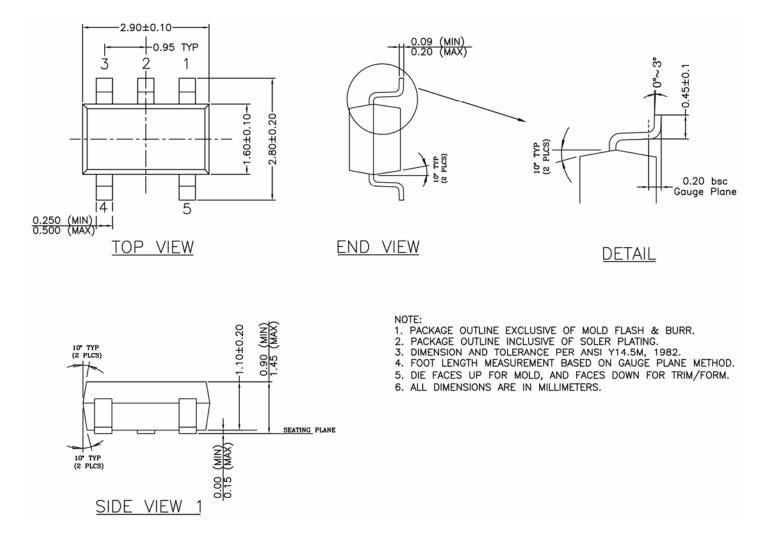


Bottom Copper



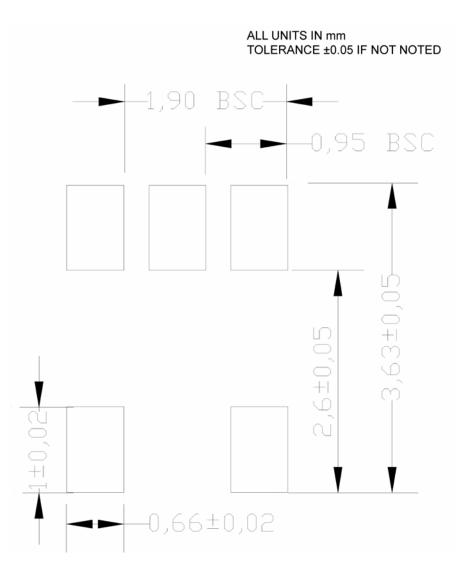
Bottom Silk Screen

Package Information



5-Pin SOT23 (SOT23-5)

Recommended Landing Pattern



MICREL, INC. 2180 FORTUNE DRIVE SAN JOSE, CA 95131 USA TEL +1 (408) 944-0800 FAX +1 (408) 474-1000 WEB http://www.micrel.com

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